



**THDT58S1  
THDT58S**

Application Specific Discretes  
A.S.D.<sup>TM</sup>

**TRANSIENT VOLTAGE SUPPRESSOR  
FOR SLIC PROTECTION**

## FEATURES

- CROWBAR PROTECTION
- DUAL ASYMMETRICAL TRANSIENT SUPPRESSOR
- PEAK PULSE CURRENT :
  - $I_{PP} = 75 \text{ A}$ , 10/1000  $\mu\text{s}$  for THDT58S.
  - $I_{PP} = 35 \text{ A}$ , 10/1000  $\mu\text{s}$  for THDT58S1.
- HOLDING CURRENT = 150 mA min
- BREAKDOWN VOLTAGE = 58 V.
- BREAKOVER VOLTAGE = 80V max

## DESCRIPTION

This device has been especially designed to protect subscriber line card interfaces (SLIC) against transient overvoltages.

Its ion-implanted technology confers its excellent electrical characteristics.

This is why this device easily fulfils the main protection standards which are related to the overvoltages suppression on telecom lines.

The product pinout is compatible with TO202 and TO220 packages.

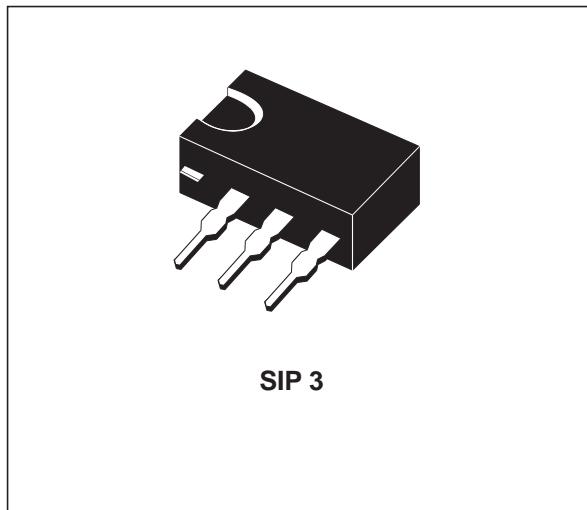
## COMPLIES WITH THE FOLLOWING STANDARDS :

|                    |                       |           |
|--------------------|-----------------------|-----------|
| <b>CCITT K20 :</b> | 10/700 $\mu\text{s}$  | 1kV       |
|                    | 5/310 $\mu\text{s}$   | 25A       |
| <b>VDE 0433 :</b>  | 10/700 $\mu\text{s}$  | 2kV       |
|                    | 5/200 $\mu\text{s}$   | 45/50A(*) |
| <b>VDE 0878 :</b>  | 1.2/50 $\mu\text{s}$  | 1.5kV     |
|                    | 1/20 $\mu\text{s}$    | 40A       |
| <b>CNET I3124:</b> | 0.5/700 $\mu\text{s}$ | 1kV       |
|                    | 0.2/310 $\mu\text{s}$ | 25A       |

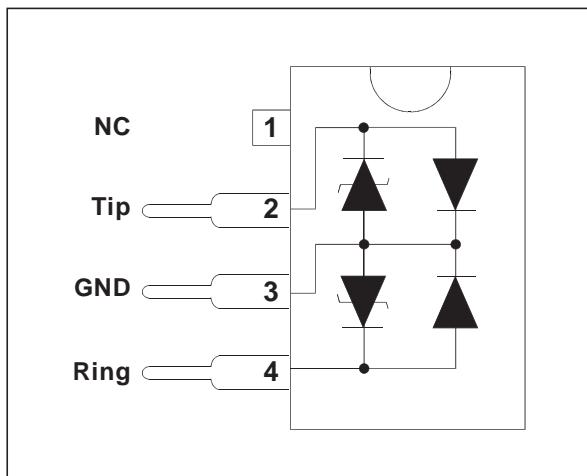
## BELLCORE

|                        |                       |            |
|------------------------|-----------------------|------------|
| <b>TR-NWT-001089 :</b> | 10/1000 $\mu\text{s}$ | 1kV        |
|                        | 10/1000 $\mu\text{s}$ | 35/75A (*) |

(\*) with series resistors or PTC.



## SCHEMATIC DIAGRAM



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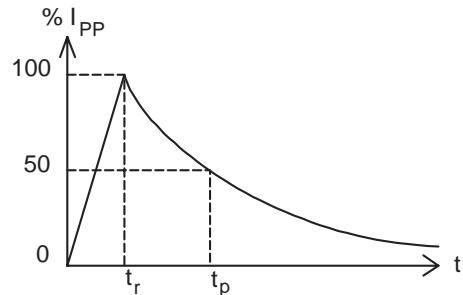
## THDT58S / THDT58S1

### ABSOLUTE MAXIMUM RATINGS ( $T_{amb} = 25^{\circ}\text{C}$ )

| Symbol             | Parameter   |   | THDT58S1            | THDT58S                                  | Unit                                     |
|--------------------|---|---|---------------------|--|--|
| $I_{PP}$           | Peak pulse current (see note 1)                                     | 10/1000 $\mu\text{s}$<br>8/20 $\mu\text{s}$<br>2/10 $\mu\text{s}$ | 35<br>70<br>80      | 75<br>150                                | A  |
| $I_{TSM}$          | Non repetitive surge peak on-state current ( $F = 50\text{Hz}$ )    | $t = 20 \text{ ms}$   | 20                  | 30                                       | A  |
| $dV/dt$            | Critical rate of rise of off-state voltage                          | 67% $V_{BR}$  |                     | 5  | kV/ $\mu\text{s}$                        |
| $T_{stg}$<br>$T_j$ | Storage temperature range<br>Maximum operating junction temperature | -55 to +150<br>+150   | -40 to +150<br>+150 | $^{\circ}\text{C}$<br>$^{\circ}\text{C}$ | $^{\circ}\text{C}$<br>$^{\circ}\text{C}$ |
| $T_L$              | Maximum lead temperature for soldering during 10s                   |   | 260                 | 260                                      | $^{\circ}\text{C}$                       |

Note 1 : Pulse waveform :

$$\begin{array}{lll} 10/1000\mu\text{s} & t_r=10\mu\text{s} & t_p=1000\mu\text{s} \\ 5/310\mu\text{s} & t_r=5\mu\text{s} & t_p=310\mu\text{s} \\ 2/10\mu\text{s} & t_r=2\mu\text{s} & t_p=10\mu\text{s} \end{array}$$

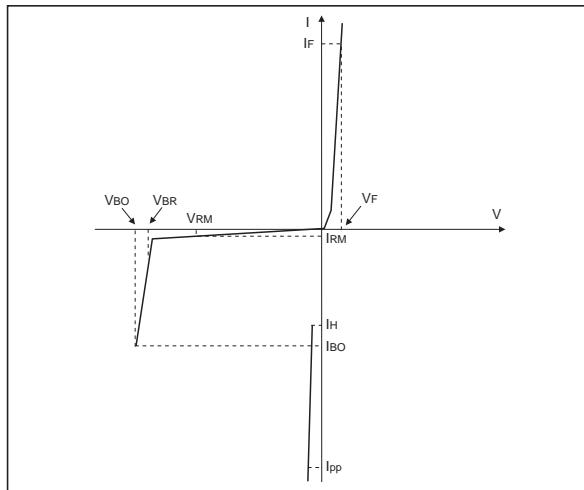


### THERMAL RESISTANCES

| Symbol         | Parameter           | Value | Unit                 |
|----------------|---------------------|-------|----------------------|
| $R_{th} (j-a)$ | Junction to ambient | 80    | $^{\circ}\text{C/W}$ |

**ELECTRICAL CHARACTERISTICS ( $T_{amb} = 25^\circ C$ )**

| Symbol   | Parameter                   |
|----------|-----------------------------|
| $V_{RM}$ | Stand-off voltage           |
| $I_{RM}$ | Leakage current at $V_{RM}$ |
| $V_{BR}$ | Breakdown voltage           |
| $V_{BO}$ | Breakover voltage           |
| $I_H$    | Holding current             |
| $V_F$    | Forward Voltage drop        |
| $I_{BO}$ | Breakover current           |
| $I_{PP}$ | Peak pulse current          |
| C        | Capacitance                 |

**1 - PARAMETER RELATED TO THE DIODE LINE/GND**

| Symbol | Test conditions                             | Value | Unit |
|--------|---|-------|------|
| $V_F$  | $I_F = 5 \text{ A}$ $t_p = 500 \mu\text{s}$ | 5     | V    |

**2 - PARAMETERS RELATED TO THE PROTECTION THYRISTOR**

| Type     | $I_{RM} @ V_{RM}$ |    | $V_{BR} @ I_R$ |    | $V_{BO} @ I_{BO}$ |     |     | $I_H$<br>min.<br>note 2 | C<br>max.<br>note 3 |
|----------|-------------------|----|----------------|----|-------------------|-----|-----|-------------------------|---------------------|
|          | $\mu\text{A}$     | V  | V              | mA | V                 | mA  | mA  |                         |                     |
| THDT58S  | 10                | 56 | 58             | 1  | 80                | 150 | 800 | 150                     | 400                 |
| THDT58S1 | 10                | 56 | 58             | 1  | 80                | 50  | 800 | 150                     | 200                 |

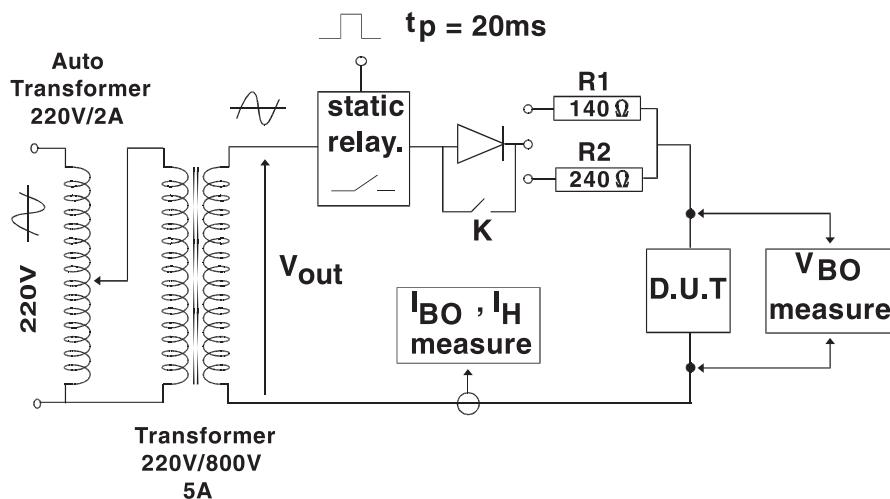
Note 1 : See the reference test circuit 1 for  $I_{BO}$  and  $V_{BO}$  parameters.

Note 2 : See test circuit 2.

Note 3 :  $V_R = 1\text{V}$ ,  $F = 1\text{MHz}$ .

## THDT58S / THDT58S1

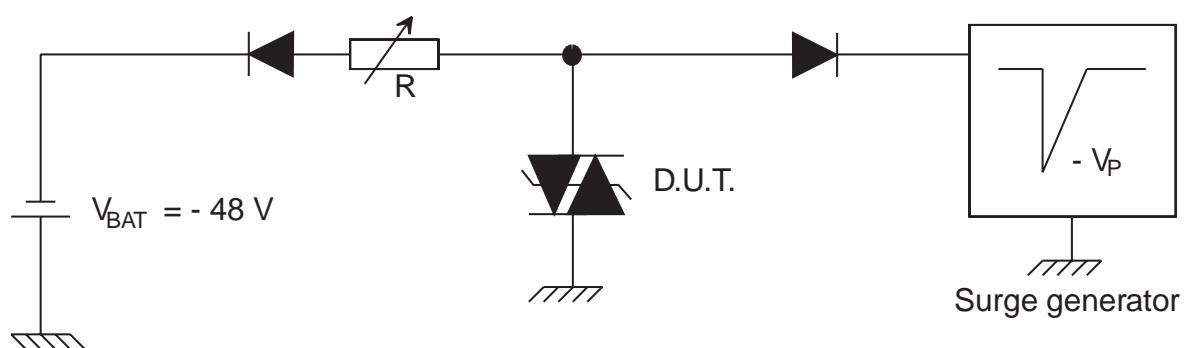
### REFERENCE TEST CIRCUIT 1 :



#### TEST PROCEDURE :

- Pulse Test duration ( $t_p = 20\text{ms}$ ):
  - For Bidirectional devices = Switch K is closed
  - For Unidirectional devices = Switch K is open.
- $V_{OUT}$  Selection
  - Device with  $V_{BO} < 200$  Volt
    - $V_{OUT} = 250 \text{ V}_{\text{RMS}}$ ,  $R_1 = 140 \Omega$ .
  - Device with  $V_{BO} \geq 200$  Volt
    - $V_{OUT} = 480 \text{ V}_{\text{RMS}}$ ,  $R_2 = 240 \Omega$ .

### FUNCTIONAL HOLDING CURRENT ( $I_H$ ) TEST CIRCUIT 2

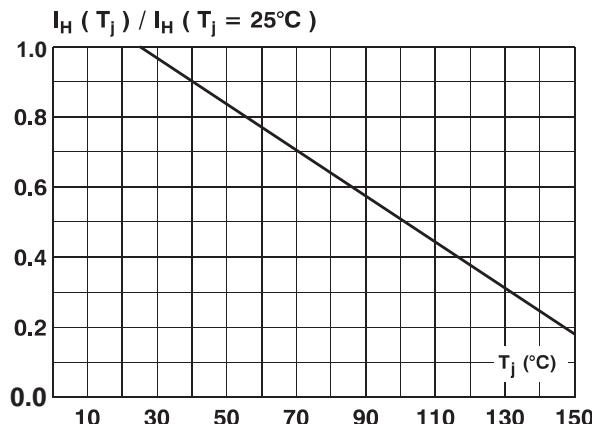


This is a GO-NOGO Test which allows to confirm the holding current ( $I_H$ ) level in a functional test circuit.

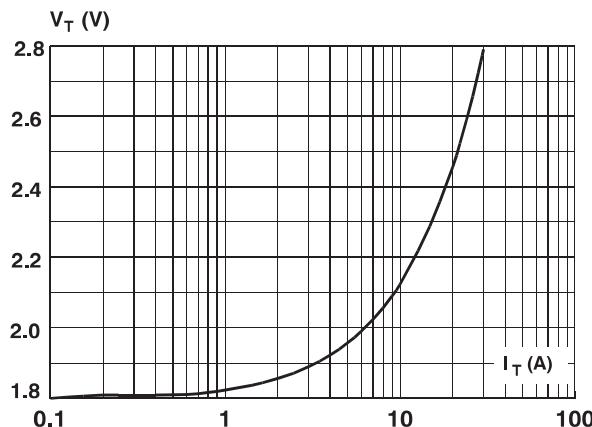
#### TEST PROCEDURE :

- 1) Adjust the current level at the  $I_H$  value by short circuiting the AK of the D.U.T.
- 2) Fire the D.U.T with a surge Current :  $I_{pp} = 10\text{A}$ ,  $10/1000 \mu\text{s}$ .
- 3) The D.U.T will come back off-state within 50 ms max.

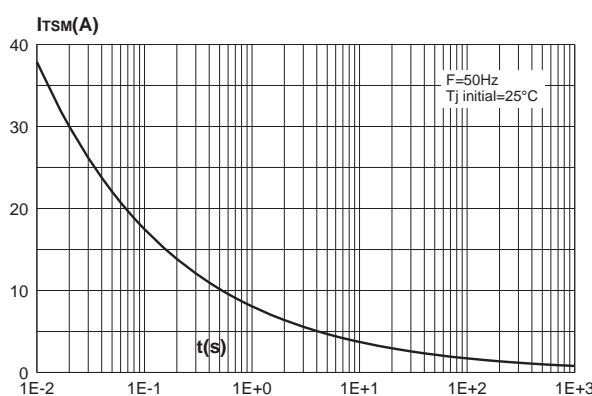
**Fig. 1:** Relative variation of holding current junction temperature.



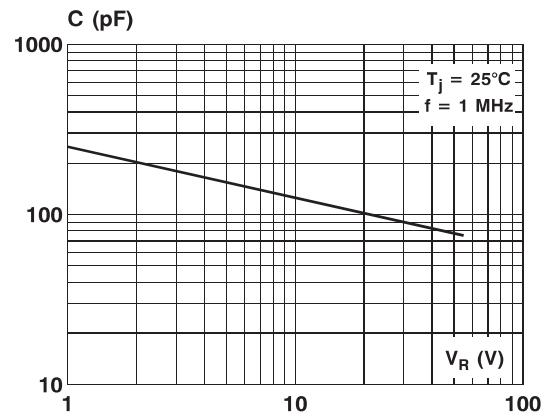
**Fig. 3:** Peak on state voltage versus peak on state current (typical values).



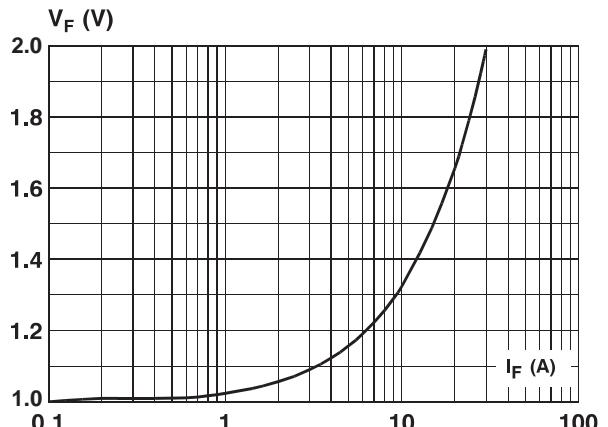
**Fig. 5:** Surge peak current versus overload duration (THDT58S).



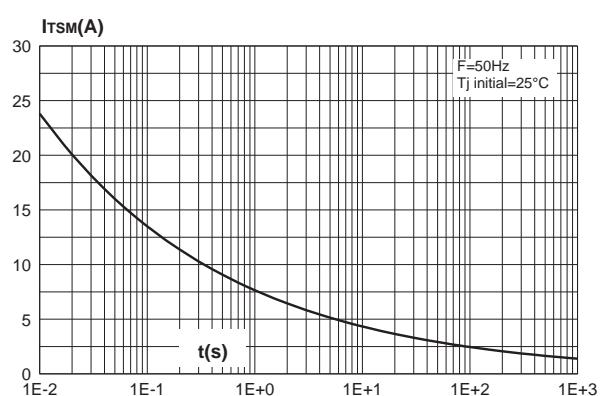
**Fig. 2:** Capacitance versus reverse applied voltage (typical values).



**Fig. 4:** Peak forward voltage drop versus peak forward current (typical values).



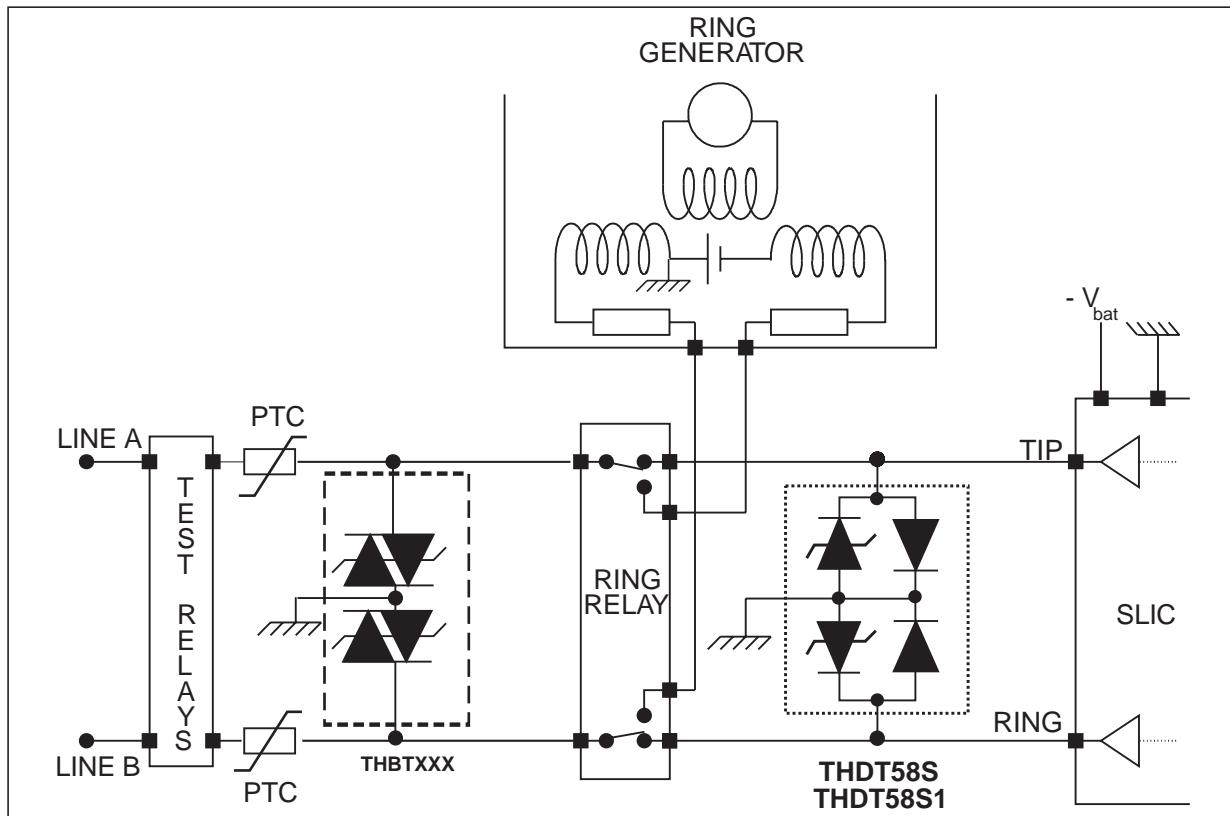
**Fig. 6:** Surge peak current versus overload duration (THDT58S1).



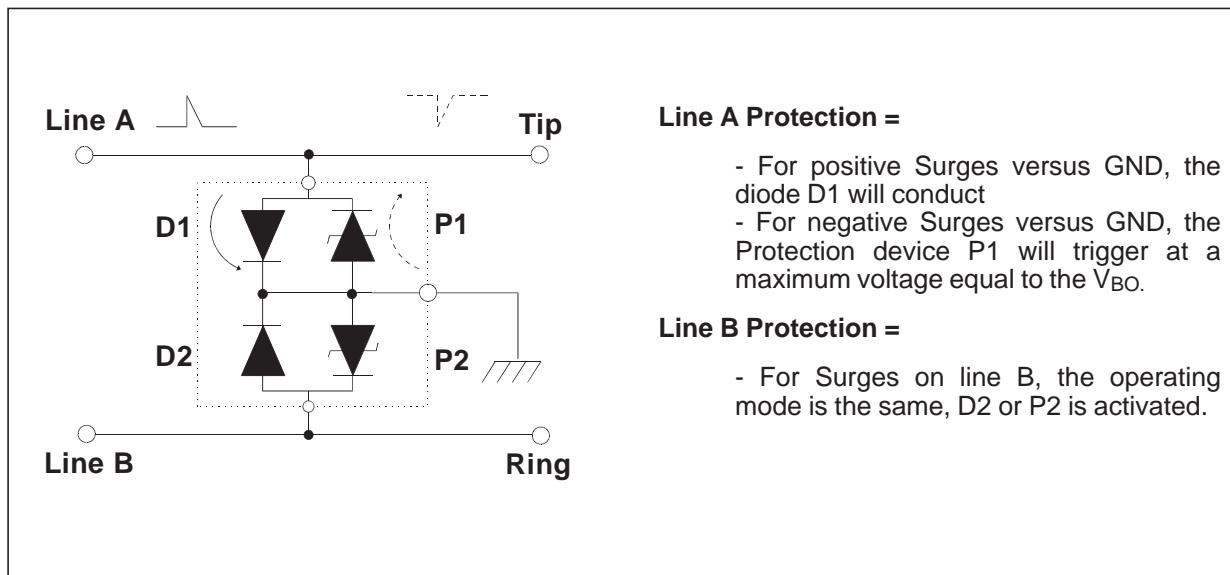
## THDT58S / THDT58S1

### APPLICATION CIRCUIT

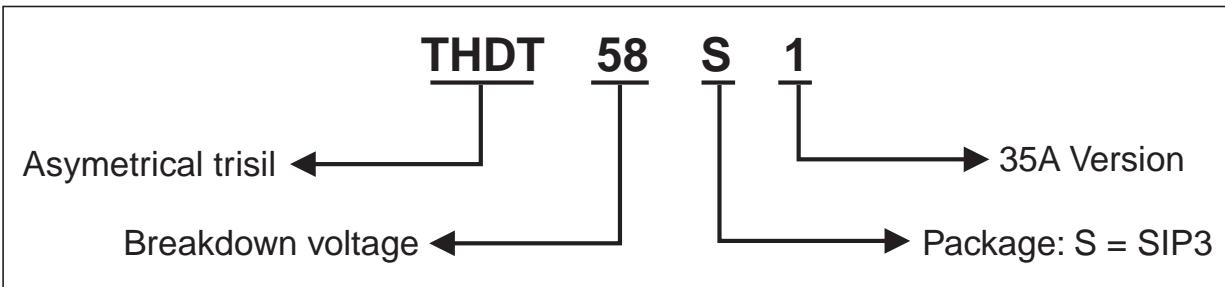
#### Typical SLIC protection concept



### FUNCTIONAL DESCRIPTION



## ORDER CODE



## MARKING

| Type     | Marking  |
|----------|----------|
| THDT58S  | THDT58S  |
| THDT58S1 | THDT58S1 |

**Packaging** : Standard packaging is in antistatic tubes

**Weight** : 0.55g

## PACKAGE MECHANICAL DATA.

SIP 3 Plastic

| REF. | DIMENSIONS  |      |       |        |       |       |
|------|-------------|------|-------|--------|-------|-------|
|      | Millimetres |      |       | Inches |       |       |
|      | Min.        | Typ. | Max.  | Min.   | Typ.  | Max.  |
| A    |             |      | 7.10  |        |       | 0.280 |
| a1   | 2.80        |      |       | 0.110  |       |       |
| a2   | 1.50        |      | 1.90  | 0.059  |       | 0.075 |
| B    |             |      | 10.15 |        |       | 0.400 |
| b1   |             | 0.50 |       |        | 0.020 |       |
| b2   | 1.35        |      | 1.75  | 0.053  |       | 0.069 |
| c1   | 0.38        |      | 0.50  | 0.015  |       | 0.020 |
| e    |             | 2.54 |       |        | 0.100 |       |
| e3   |             | 7.62 |       |        | 0.200 |       |
| I    |             |      | 10.50 |        |       | 0.413 |
| L    |             | 3.30 |       |        | 0.130 |       |
| Z    |             |      | 1.50  |        |       | 0.059 |

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